

HAT1072H

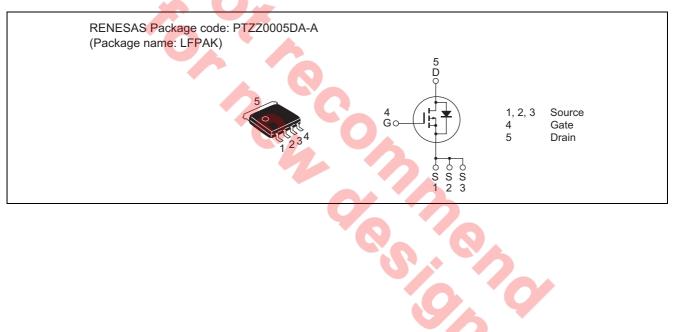
Silicon P Channel Power MOS FET Power Switching

REJ03G1155-0700 (Previous: ADE-208-1534E) Rev.7.00 Sep 07, 2005

Features

- Capable of -4.5 V gate drive
- Low drive current
- High density mounting
- Low on-resistance
 - $R_{DS (on)} = 3.6 \text{ m}\Omega \text{ typ} (\text{at } V_{GS} = -10 \text{ V})$

Outline





Absolute Maximum Ratings

$(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-30	V
Gate to source voltage	V _{GSS}	-20 / +10	V
Drain current	ID	-40	A
Drain peak current	I _{D (pulse)} Note 1	-160	A
Body-drain diode reverse drain current	I _{DR}	-40	A
Channel dissipation	Pch Note 2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Tc = 25°C

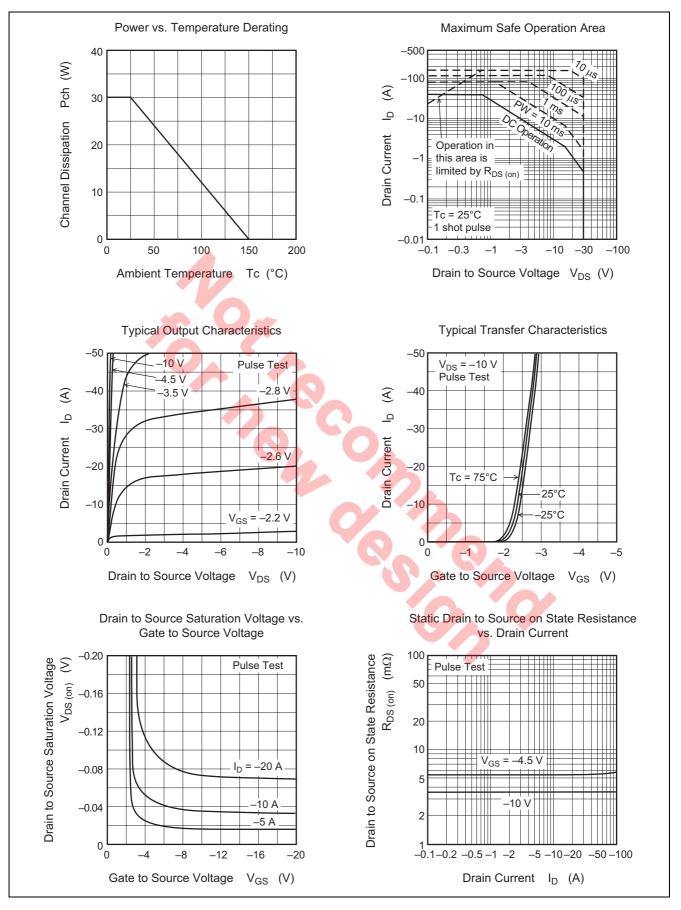
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	-30	_	—	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	—		±0.1	μΑ	$V_{GS} = -20, +10 \text{ V}, \text{ V}_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—		-1	μΑ	$V_{DS} = -30 V, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-0.5		-2.0	V	$V_{DS} = -10 V$, $I_{D} = -1 mA$
Static drain to source on state	R _{DS (on)}		3.6	4.5	mΩ	$I_D = -20 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 3}}$
resistance	R _{DS (on)}		5.3	7.7	mΩ	$I_D = -20 \text{ A}, V_{GS} = -4.5 \text{ V}^{Note 3}$
Forward transfer admittance	y _{fs}	36	60	—	S	$I_D = -20 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss		9500	—	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	—	1300	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		700		pF	f = 1 MHz
Total gate charge	Qg	_	155		nC	$V_{DD} = -10 \text{ V}$
Gate to source charge	Qgs		28		nC	$V_{GS} = -10 V$
Gate to drain charge	Qgd	_	26		nC	$I_D = -40 \text{ A}$
Turn-on delay time	t _{d (on)}	—	28		ns	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -20 \text{ A},$
Rise time	tr	—	60		ns	V _{DD} ≅ -10 V
Turn-off delay time	t _{d (off)}	—	305		ns	$R_L = 0.5 \Omega$
Fall time	t _f	—	140		ns	$Rg = 4.7 \Omega$
Body-drain diode forward voltage	V _{DF}	_	0.87	1.14	V	$I_F = -40 \text{ A}, V_{GS} = 0^{\text{Note 3}}$
Body-drain diode reverse recovery	t _{rr}	_	110		ns	$I_F = -40 \text{ A}, V_{GS} = 0$
time						di _F /dt = 100 A/µs

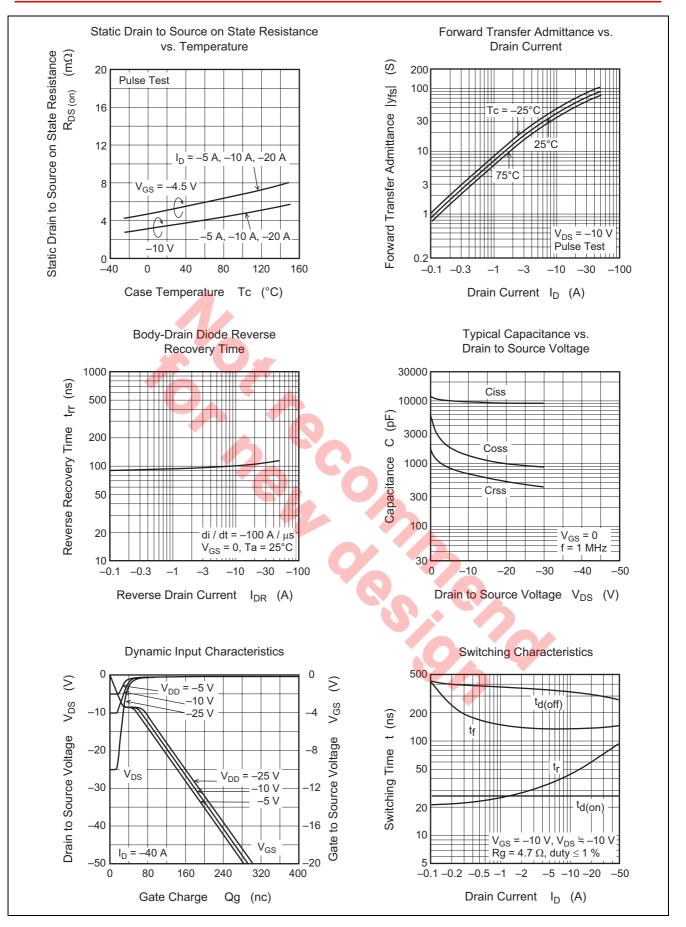
Note: 3. Pulse test



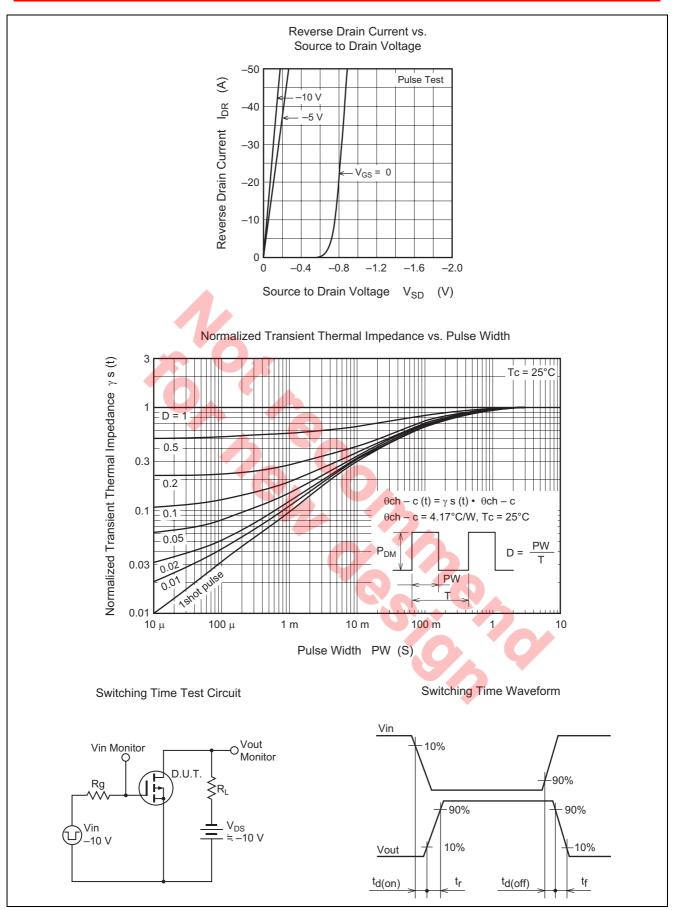
Main Characteristics





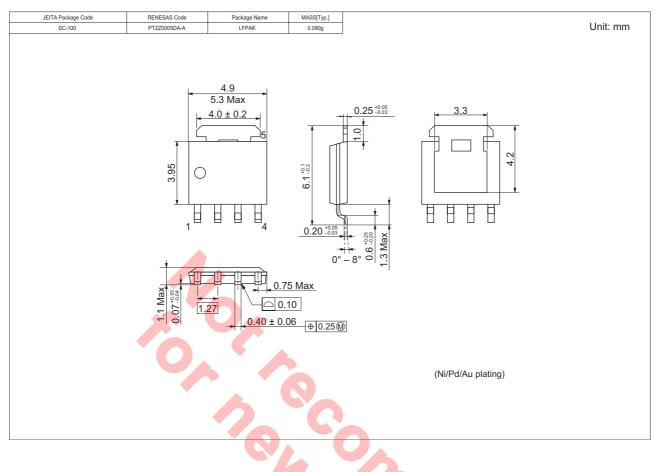








Package Dimensions



Ordering Information

Part Name	Quantity		Shipp	bing Container
HAT1072H-EL-E	2500 pcs	Taping		

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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